Features

- Half-bridge SCR configuration integrated in a single package
- With high thermal conductivity DBC as the Insulation
- Welding by vacuum welding technology, which provide high reliability

Product Summary

Applications

- Temperature control

[redacted]

Absolute Maximum Ratings (@ T_C = 25°C unless otherwise specified)

Parameter	Conditions	Symbol	Values	Unit

Electrical Characteristics (@ T_C = 25°C unless otherwise specified)

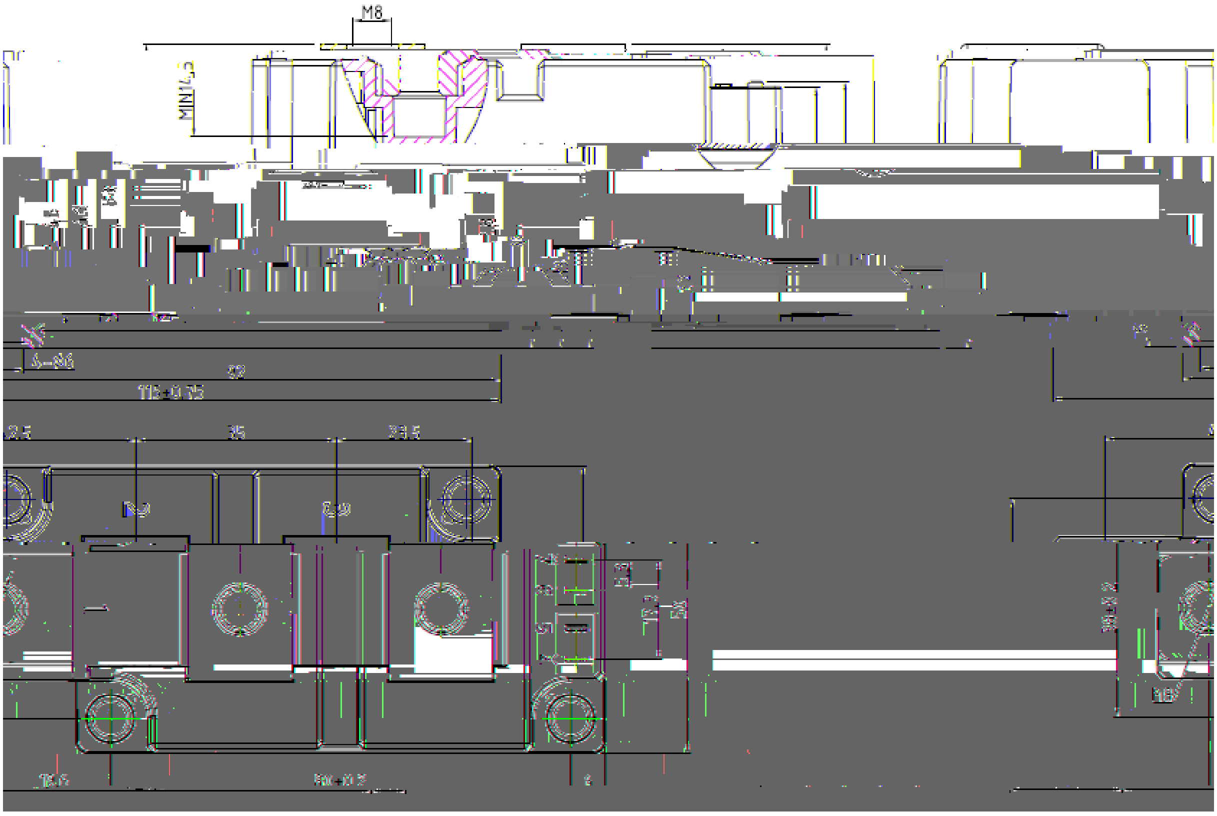
Parameter	Conditions	

Ordering Information

Device	Marking	Package	Weight	Inner Box	

Circuit Diagram

Package Outlines (mm)



Package Outlines (mm)

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